

## Electronic Patent Application Fee Transmittal

Application Number:	10830188			
Filing Date:	21-Apr-2004			
Title of Invention:	Method for accommodating small minimum die in wire bonded area array packages			
First Named Inventor/Applicant Name:	Ryan Lane			
Filer:	William M. Hooks/Sheryl Schoen			
Attorney Docket Number:	020378D1			

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 5 months with \$0 paid	1255	1	2350	2350
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>2350</b>